

**AMENDMENTS TO THE CLAIMS**

1-17. (Canceled)

18. (Previously Presented) An imaging device, comprising:

a die containing an array of imaging elements; and

a transparent element adhesively attached to said die by an adhesive material and having a first surface facing a first surface of said die, said first surface of said die having at least one adhesive flow restriction area for impeding flow of an adhesive across said first surface of said die, wherein said adhesive flow restriction area comprises at least one trench.

19. (Original) The imaging device of claim 18, wherein said at least one trench has a curved shape.

20. (Original) The imaging device of claim 18, wherein said at least one trench creates a perimeter around said array of imaging elements

21. (Original) The imaging device of claim 20, further comprising a second trench creating a perimeter around said at least one trench.

22. (Original) The imaging device of claim 18, wherein said at least one trench extends from edge to edge of said die.

23-62. (Canceled)

63. (Previously Presented) The imaging device of claim 18, wherein said transparent element is comprised of a material selected from the group consisting of glass, an optical thermoplastic material, a polyimide, a thermoset resin, a photosensitive gelatin, and a radiation curable resin.

64. (Previously Presented) The imaging device of claim 18, wherein said adhesive material at an edge of said transparent element completely covers wire bonds electrically connecting said die to conductive lines.

65. (Previously Presented) The imaging device of claim 18, wherein said die is associated with a substrate.

66. (Previously Presented) The imaging device of claim 18, wherein said die is electrically connected to conductive tape by at least one conductive structure.

67. (Previously Presented) The imaging device of claim 66, wherein said at least one conductive structure is a solder ball.

68. (Previously Presented) The imaging device of claim 18, wherein said imaging element is comprised of an array of pixels, said pixels providing electrical signals corresponding to a response from light radiation.

69. (Previously Presented) The imaging device of claim 18, wherein said imaging element is comprised of an array of pixels, said pixels capable of displaying an image corresponding to electrical signals.

70. (Previously Presented) The imaging device of claim 18, wherein a vacant space between said transparent element and said array of imaging elements is hermetically sealed by said adhesive material.

71-78 (Cancelled).